TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (U-MOS III)

2SK3847

Switching Regulator, DC/DC Converter and Motor Drive Applications

• Low drain-source ON resistance : RDS (ON) = $12 \text{ m}\Omega$ (typ.)

• High forward transfer admittance $: |Y_{fs}| = 36 \text{ S (typ.)}$ • Low leakage current $: I_{DSS} = 100 \text{ }\mu\text{A (max) (V}_{DS} = 40 \text{ V)}$

• Enhancement mode $: V_{th} = 1.5 \text{ to } 2.5 \text{ V}$

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

| Characte | eristic | Symbol | Rating | Unit | |
|--|----------------|------------------|---------|------|--|
| Drain-source voltage | | V_{DSS} | 40 | ٧ | |
| Drain-gate voltage (R _{GS} = 20 kΩ) | | V_{DGR} | 40 | V | |
| Gate-source voltage | | V_{GSS} | ±20 | V | |
| Drain current | DC (Note 1) | I _D | 32 | Α | |
| | Pulse (Note 1) | I _{DP} | 96 | А | |
| Drain power dissipation | | P_{D} | 30 | W | |
| Single-pulse avalanche energy (Note 2) | | E _{AS} | 47 | mJ | |
| Avalanche current | | I _{AR} | 32 | Α | |
| Repetitive avalanche energy (Note 3) | | E _{AR} | 3 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature range | | T _{stg} | -55~150 | °C | |

Thermal Characteristics

| Characteristic | Symbol | Max | Unit |
|--|------------------------|------|------|
| Thermal resistance, channel to case | R _{th (ch-c)} | 4.17 | °C/W |
| Thermal resistance, channel to ambient | R _{th (ch-a)} | 83.3 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

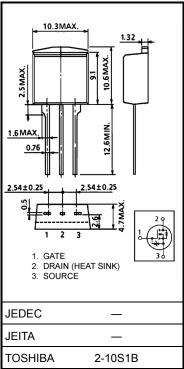
Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 48 μ H, RG = 25 Ω , IAR = 32 A

Note 3: Repetitive rating; pulse width limited by maximum channel temperature

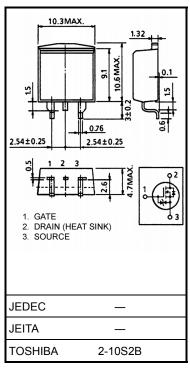
This transistor is an electrostatic-sensitive device. Handle with care.

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Unit: mm



Weight: 1.5 g (typ.)



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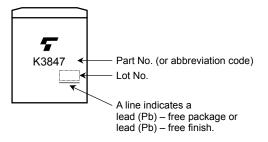
Electrical Characteristics (Ta = 25°C)

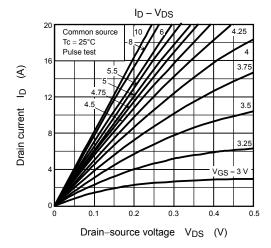
| Chara | cteristic | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|---------------------------------|-----------------------|--|------|------|-----|----------|
| Gate leakage cu | ırrent | I _{GSS} | V _{GS} = ±16 V, V _{DS} = 0 V | _ | _ | ±10 | μΑ |
| Drain cutoff curr | rent | I _{DSS} | V _{DS} = 40 V, V _{GS} = 0 V | | _ | 100 | μA |
| Drain-source br | eakdown voltage | V _{(BR) DSS} | I _D = 10 mA, V _{GS} = 0 V | 40 | _ | _ | V |
| Diam Source bi | Drain-source breakdown voltage | | I_D = 10 mA, V_{GS} = -20 V | 15 | _ | _ | v |
| Gate threshold | voltage | V_{th} | V _{DS} = 10 V, I _D = 1 mA | 1.5 | _ | 2.5 | V |
| Drain-course O | Drain-source ON resistance | | V _{GS} = 4.5 V, I _D = 16 A | _ | 19 | 26 | mΩ |
| Diain-source O | | | V _{GS} = 10 V, I _D = 16 A | _ | 12 | 16 | |
| Forward transfe | r admittance | Y _{fs} | V _{DS} = 10 V, I _D = 16 A | 18 | 36 | _ | S |
| Input capacitano | tt capacitance C _{iss} | | _ | 1980 | _ | | |
| Reverse transfer capacitance | | C _{rss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | _ | 210 | _ | pF |
| Output capacitance | | Coss | | _ | 300 | _ | |
| Switching time | Rise time | t _r | 10 V VGS 0 V D = 16 A Output VDD ≈ 20 V | _ | 7 | _ | |
| | Turn-on time | t _{on} | | _ | 22 | _ | ns |
| | Fall time | t _f | | _ | 10 | _ | 113 |
| | Turn-off time | t _{off} | Duty ≤ 1%, t _w = 10 μs | | 60 | _ | <u> </u> |
| Total gate charge (gate-source plus gate-drain) | | Qg | | | 40 | | |
| Gate-source ch | Gate-source charge | | $V_{DD} \approx 32 \text{ V, } V_{GS} = 10 \text{ V, } I_D = 32 \text{ A}$ | | 28 | _ | nC |
| Gate-drain ("Mi | Gate-drain ("Miller") charge | | | _ | 12 | _ | |

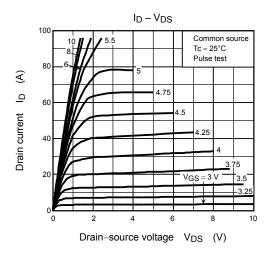
Source-Drain Ratings and Characteristics (Ta = 25°C)

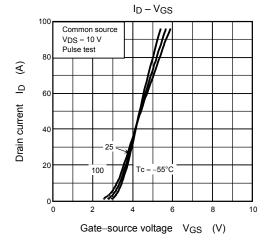
| Characteristic | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|---|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I _{DR} | _ | _ | _ | 32 | Α |
| Pulse drain reverse current (Note 1) | I _{DRP} | _ | _ | _ | 96 | Α |
| Forward voltage (diode) | V _{DSF} | I _{DR} = 32 A, V _{GS} = 0 V | _ | _ | -1.5 | V |
| Reverse recovery time | t _{rr} | I _{DR} = 32 A, V _{GS} = 0 V | | 40 | | ns |
| Reverse recovery charge | Qrr | dl _{DR} /dt = 50 A/μS | _ | 24 | | nC |

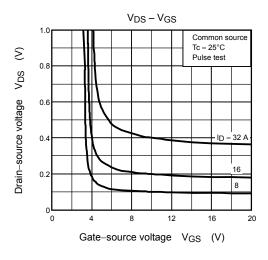
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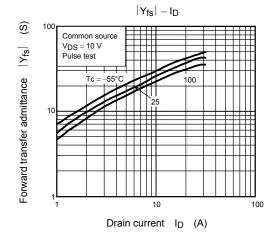


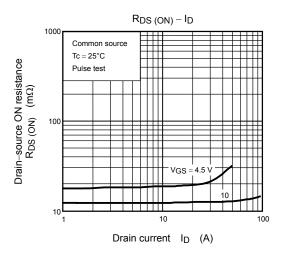




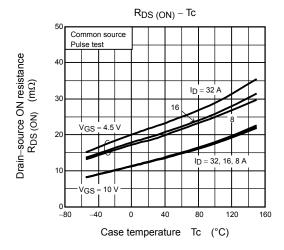


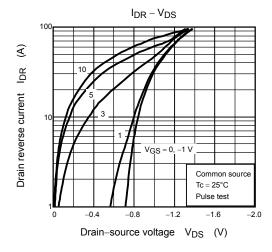


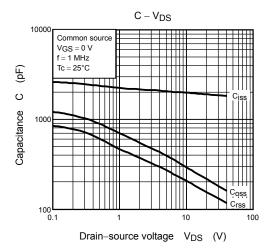


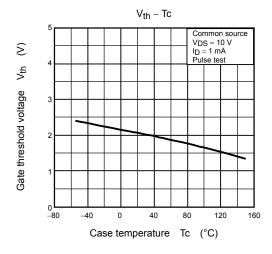


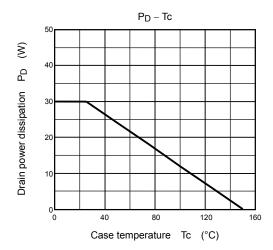
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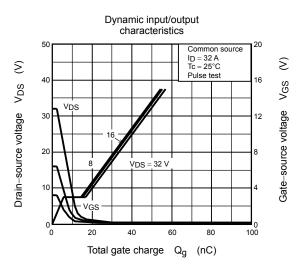


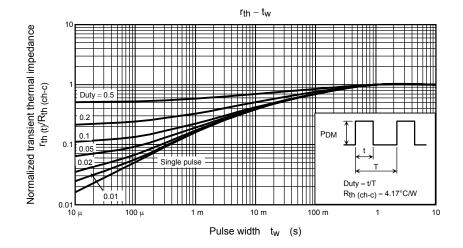


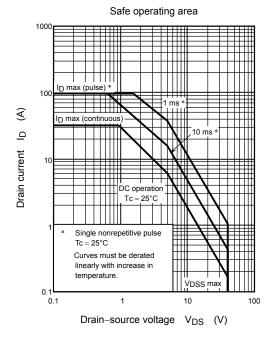


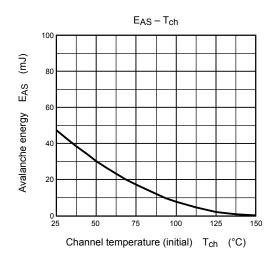


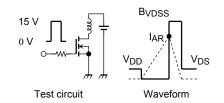












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 25~V,~L = 48~\mu H \end{aligned}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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